

ELECTRONIC PACKAGE WITH STACKED
CONNECTIONS AND METHOD FOR MAKING SAME

ABSTRACT

An electronic package which includes first and second circuitized substrates secured
5 together by a solder member which includes a first contact portion for attachment to a printed
circuit board and a second contact portion used to bond the two substrates together (e.g., to form
a multi-chip module). Semiconductor chips can be positioned on and electrically coupled to the
formed solder members.

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